



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE4678GM			<b>Issued</b>	24. January 2018			
<b>MA#</b>	MA001154500							
<b>Package</b>	PG-DSO-14-30			<b>Weight*</b>	143.30 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.312	2.31	2.31	23115	23115
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		421	
	non noble metal	iron	7439-89-6	1.207	0.84		8423	
wire	non noble metal	copper	7440-50-8	49.007	34.20	35.09	342001	350950
	noble metal	gold	7440-57-5	0.273	0.19	0.19	1907	1907
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1195
	plastics	epoxy resin	-	7.879	5.50		54987	
	inorganic material	silicondioxide	60676-86-0	77.595	54.15	59.77	541507	597689
leadfinish	non noble metal	tin	7440-31-5	1.241	0.87	0.87	8664	8664
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7186	7186
glue	plastics	acrylic resin	-	0.331	0.23		2308	
	noble metal	silver	7440-22-4	1.172	0.82	1.05	8181	10489
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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